

# Session 6: New Chemistries and Tools for Supercritical CO<sub>2</sub> Processing of Thin Films

- *Introduction (5 min)* – Anthony Muscat (UA)
- *Overview of Dual Damascene Cu/Low-k Interconnect (20 min)*  
Josh Wolf (ISMT/Intel)
- *Supercritical CO<sub>2</sub> – Tools & Applications for Semiconductor Processing (25 min)*  
Laura Rothman (Supercritical Fluids Inc.)
- *NSF STC for Environmentally Responsible Solvents and Processes (25 min)*  
Joe DeSimone (UNC-Chapel Hill/NC State/Micell)
- *Post Ash and Post Etch Cleaning using Supercritical CO<sub>2</sub> (25 min)*  
Gunilla Jacobsen (Supercritical Systems Inc.)
- *Research Update (20 min)* Chris Ober (Cornell) & Anthony Muscat (UA)
- *Panel Discussion (30 min): Speakers + Max Biberger (Supercritical Systems Inc.)*